

Super SIDELED® High-Current LED

LG A672, LP A672



**Abgekündigt nach PD_078_02 - werden durch
LG A676 und LP A676 ersetzt werden**
**Obsolete acc. to PD_078_02 - will be replaced by
LG A676 and LP A676**

Besondere Merkmale

- **Gehäusotyp:** weißes SMT Gehäuse
- **Besonderheit des Bauteils:** Abstrahlung parallel zur Platine, deshalb ideal zur Einkopplung in Lichtleiter; höherer zulässiger Betriebsstrom
- **Wellenlänge:** 570 nm (grün), 560 nm (pure green)
- **Abstrahlwinkel:** Lambertscher Strahler (120°)
- **Technologie:** GaAsP (grün), GaP (pure green)
- **optischer Wirkungsgrad:** 1,5 lm/W (grün), 0,6 lm/W (pure green)
- **Gruppierungsparameter:** Lichtstärke
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten und Wellenlöten (TTW)
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 12 mm Gurt mit 2000/Rolle, ø330 mm

Anwendungen

- Hinterleuchtung (LCD, Schalter, Tasten, Displays)
- Einkopplung in Lichtleiter
- Innenbeleuchtung im Automobilbereich (z.B. Instrumentenbeleuchtung, u.ä.)

Features

- **package:** white SMT package
- **feature of the device:** radiation direction parallel to PCB, so an ideal LED for coupling in light guides; higher permissible current
- **wavelength:** 570 nm (green), 560 nm (pure green)
- **viewing angle:** Lambertian Emitter (120°)
- **technology:** GaAsP (green), GaP (pure green)
- **optical efficiency:** 1.5 lm/W (green), 0.6 lm/W (pure green)
- **grouping parameter:** luminous intensity
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering and TTW soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 12 mm tape with 2000/reel, ø330 mm

Applications

- backlighting (LCD, switches, keys, displays)
- coupling into light guide
- interior automotive lighting. (e.g. dashboard backlighting, etc.)

Type	Emissions- farbe	Farbe der Lichtaustritts- fläche	Lichtstärke	Lichtstrom	Bestellnummer
Type	Color of Emission	Color of the Light Emitting Area	Luminous Intensity $I_F = 50 \text{ mA}$ $I_V \text{ (mcd)}$	Luminous Flux $I_F = 50 \text{ mA}$ $\Phi_V \text{ (mlm)}$	Ordering Code
■ LG A672-P1Q1-1	green	colorless clear	45.0 ... 90.0	190 (typ.)	Q62703Q5000
■ LG A672-Q1R2-1			71.0 ... 180.0	350 (typ.)	Q62703Q5001
■ LP A672-L2M2-1	pure green	colorless clear	14.0 ... 28.0	62 (typ.)	Q62703Q5056
■ LP A672-M2P1-1			22.4 ... 56.0	110 (typ.)	Q62703Q5057

- Abgekündigt nach PD_078_02 - werden durch LG_LP A676 ersetzt werden
 Obsolete acc. to PD_078_02 - will be replaced by LG_LP A676
 Letzte Bestellung / Last Order: 30.09.2003
 Letzte Lieferung / Last Delivery: 31.03.2004

Anm.: -1 gesamter Farbbereich (siehe **Seite 4**)

*Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 3 bzw. 4 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.
 In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.*

Note: -1 Total color tolerance range (siehe **page 4**)

*The standard shipping format for serial types includes a lower or upper family group of 3 or 4 individual groups. Individual half groups are not available.
 No packing unit / tape ever contains more than one luminous intensity half group.*

**Grenzwerte
Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebstemperatur Operating temperature range	T_{op}	– 40 ... + 100	°C
Lagertemperatur Storage temperature range	T_{stg}	– 40 ... + 100	°C
Sperrschichttemperatur Junction temperature	T_j	+ 100	°C
Durchlassstrom Forward current	I_F	50	mA
Stoßstrom Surge current $t \leq 10 \mu s, D = 0.005$	I_{FM}	1	A
Sperrspannung ¹⁾ Reverse voltage	V_R	12	V
Leistungsaufnahme Power consumption	P_{tot}	160	mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient Sperrschicht/Lötpad Junction/solder point Montage auf PC-Board FR 4 (Padgröße $\geq 16 \text{ mm}^2$) mounted on PC board FR 4 (pad size $\geq 16 \text{ mm}^2$)	$R_{th JA}$ $R_{th JS}$	330 100	K/W K/W

¹⁾ für kurzzeitigen Betrieb geeignet / suitable for short term application

Kennwerte ($T_A = 25\text{ °C}$)
Characteristics

Bezeichnung Parameter	Symbol Symbol	Werte Values		Einheit Unit
		LG	LP	
Wellenlänge des emittierten Lichtes (typ.) Wavelength at peak emission $I_F = 50\text{ mA}$	λ_{peak}	572	557	nm
Dominantwellenlänge ¹⁾ (typ.) Dominant wavelength $I_F = 50\text{ mA}$	λ_{dom}	570 ± 6	560 ± 6	nm
Spektrale Bandbreite bei 50 % $I_{\text{rel max}}$ (typ.) Spectral bandwidth at 50 % $I_{\text{rel max}}$ $I_F = 50\text{ mA}$	$\Delta\lambda$	25	22	nm
Abstrahlwinkel bei 50 % I_V (Vollwinkel) (typ.) Viewing angle at 50 % I_V (typ.)	2ϕ	120	120	Grad deg.
Durchlassspannung ²⁾ (typ.) Forward voltage (max.) $I_F = 50\text{ mA}$	V_F V_F	2.6 3.5	2.6 2.7	V V
Sperrstrom (typ.) Reverse current (max.) $V_R = 12\text{ V}$	I_R I_R	0.01 10	0.01 10	μA μA
Temperaturkoeffizient von λ_{peak} (typ.) Temperature coefficient of λ_{peak} $I_F = 50\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{peak}}}$	0.11	0.11	nm/K
Temperaturkoeffizient von λ_{dom} (typ.) Temperature coefficient of λ_{dom} $I_F = 50\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{dom}}}$	0.07	0.05	nm/K
Temperaturkoeffizient von V_F (typ.) Temperature coefficient of V_F $I_F = 50\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	TC_V	- 2.0	- 2.0	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 50\text{ mA}$	η_{opt}	1.5	0.6	lm/W

¹⁾ Wellenlängen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 1\text{ nm}$ ermittelt.
Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of $\pm 1\text{ nm}$.

²⁾ Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von $\pm 0,1\text{ V}$ ermittelt.
Voltages are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.1\text{ V}$.

Helligkeits-Gruppierungsschema
Luminous Intensity Groups

Lichtgruppe Luminous Intensity Group	Lichtstärke Luminous Intensity I_v (mcd)	Lichtstrom Luminous Flux Φ_v (lm)
L2	14.0 ... 18.0	50 (typ.)
M1	18.0 ... 22.4	60 (typ.)
M2	22.4 ... 28.0	75 (typ.)
N1	28.0 ... 35.5	95 (typ.)
N2	35.5 ... 45.0	120 (typ.)
P1	45.0 ... 56.0	150 (typ.)
P2	56.0 ... 71.0	190 (typ.)
Q1	71.0 ... 90.0	240 (typ.)
Q2	90.0 ... 112.0	300 (typ.)
R1	112.0 ... 140.0	380 (typ.)
R2	140.0 ... 180.0	480 (typ.)

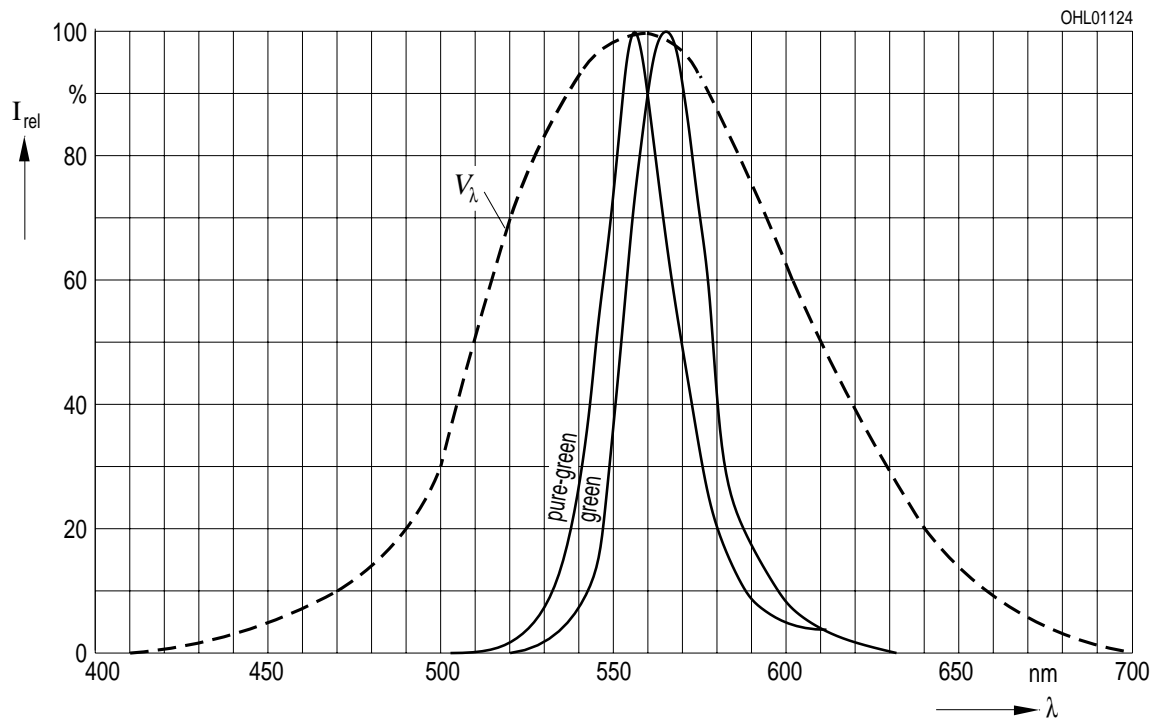
Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von $\pm 11\%$ ermittelt.
 Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of $\pm 11\%$.

Relative spektrale Emission $I_{\text{rel}} = f(\lambda)$, $T_A = 25^\circ\text{C}$, $I_F = 50\text{ mA}$

Relative Spectral Emission

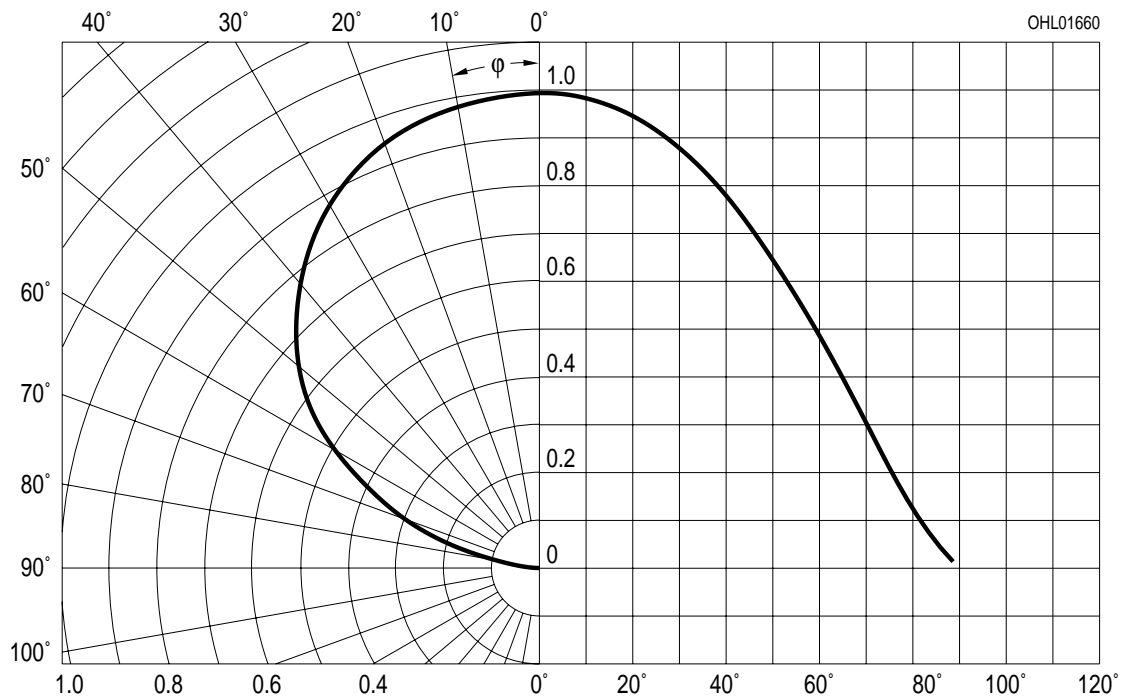
$V(\lambda)$ = spektrale Augenempfindlichkeit

Standard eye response curve



Abstrahlcharakteristik $I_{\text{rel}} = f(\varphi)$

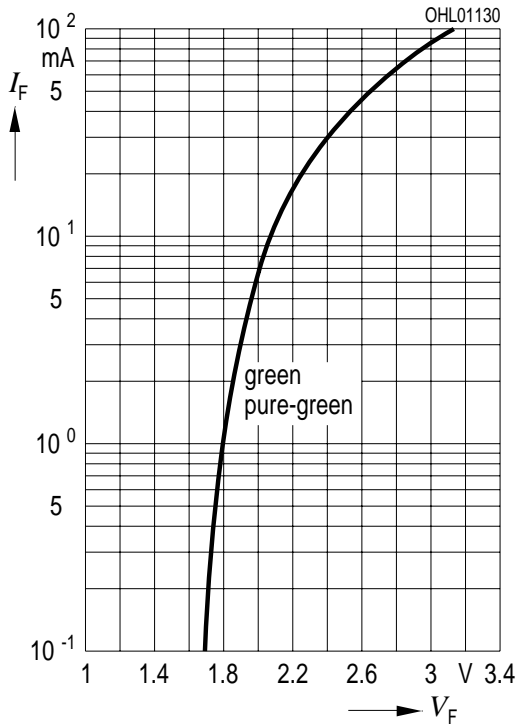
Radiation Characteristic



Durchlassstrom $I_F = f(V_F)$

Forward Current

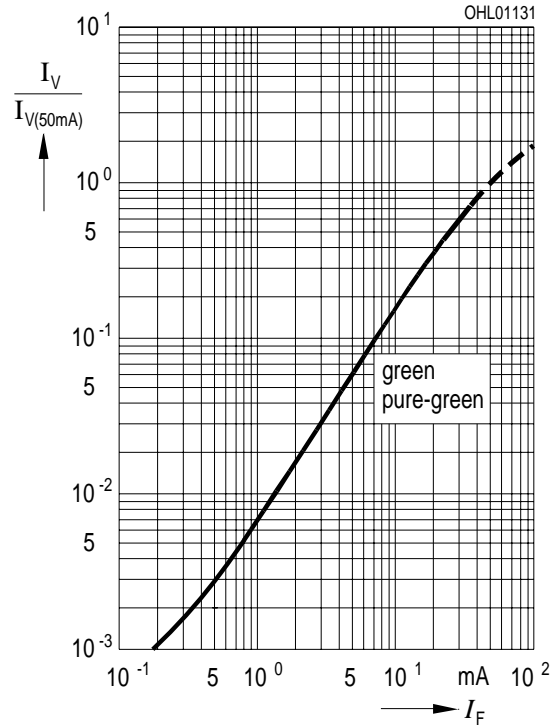
$T_A = 25^\circ\text{C}$



Relative Lichtstärke $I_V/I_{V(50\text{ mA})} = f(I_F)$

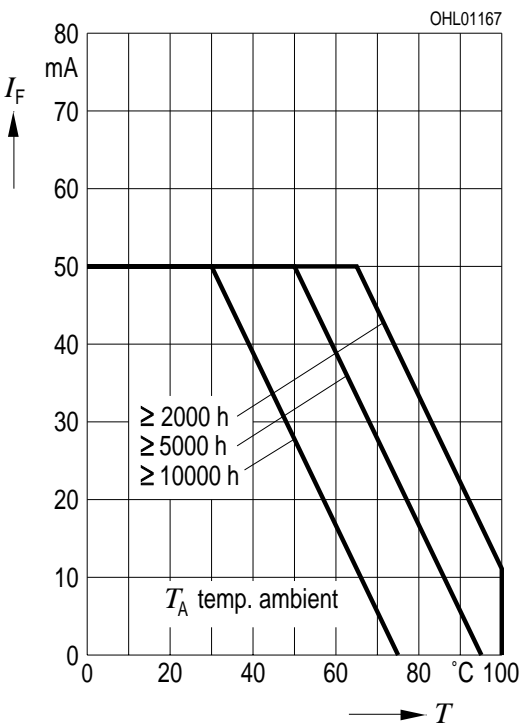
Relative Luminous Intensity

$T_A = 25^\circ\text{C}$



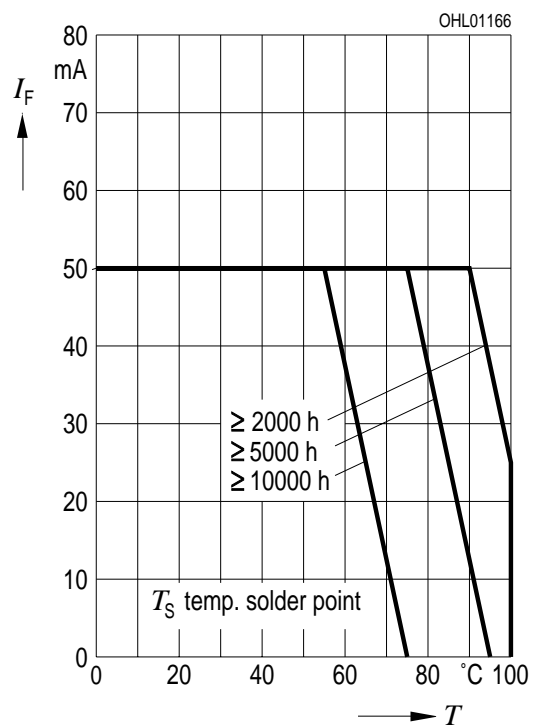
Maximal zulässiger Durchlassstrom $I_F = f(T)$

Max. Permissible Forward Current



Maximal zulässiger Durchlassstrom $I_F = f(T)$

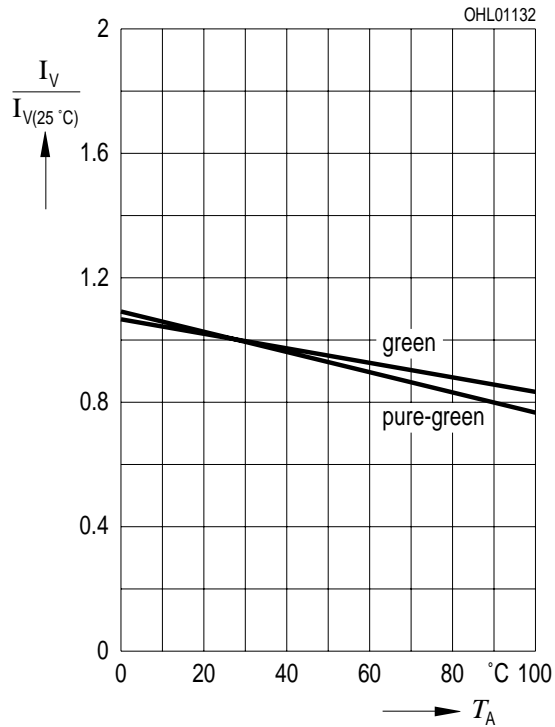
Max. Permissible Forward Current



Relative Lichtstärke $I_V/I_{V(25\text{ °C})} = f(T_A)$

Relative Luminous Intensity

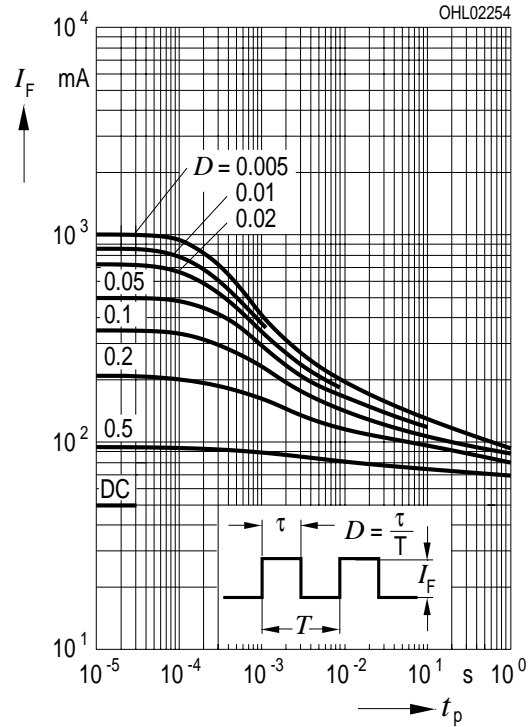
$I_F = 50\text{ mA}$



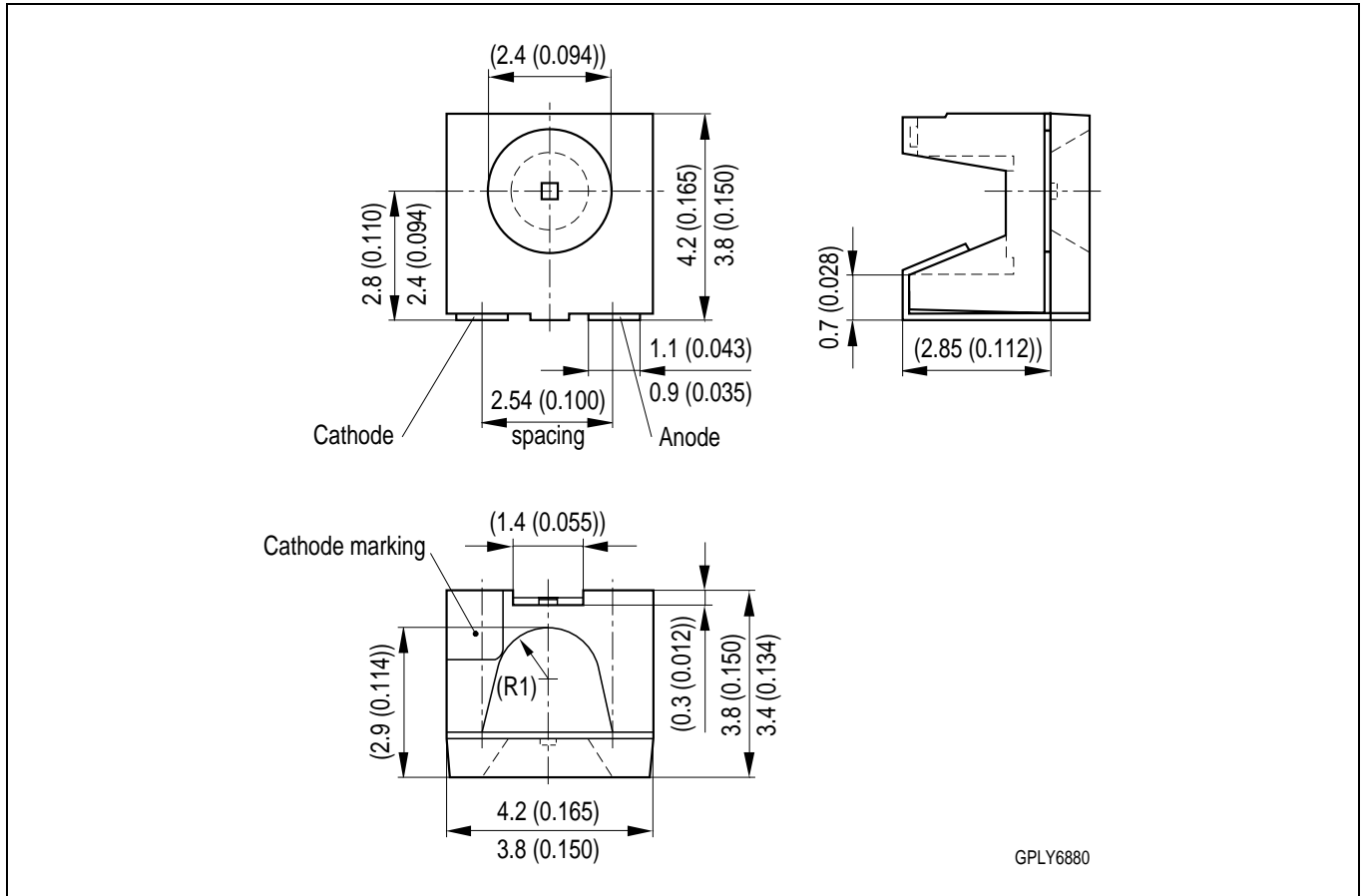
Zulässige Impulsbelastbarkeit $I_F = f(t_p)$

Permissible Pulse Handling Capability

Duty cycle $D = \text{parameter}$, $T_A = 25\text{ °C}$



**Maßzeichnung
Package Outlines**

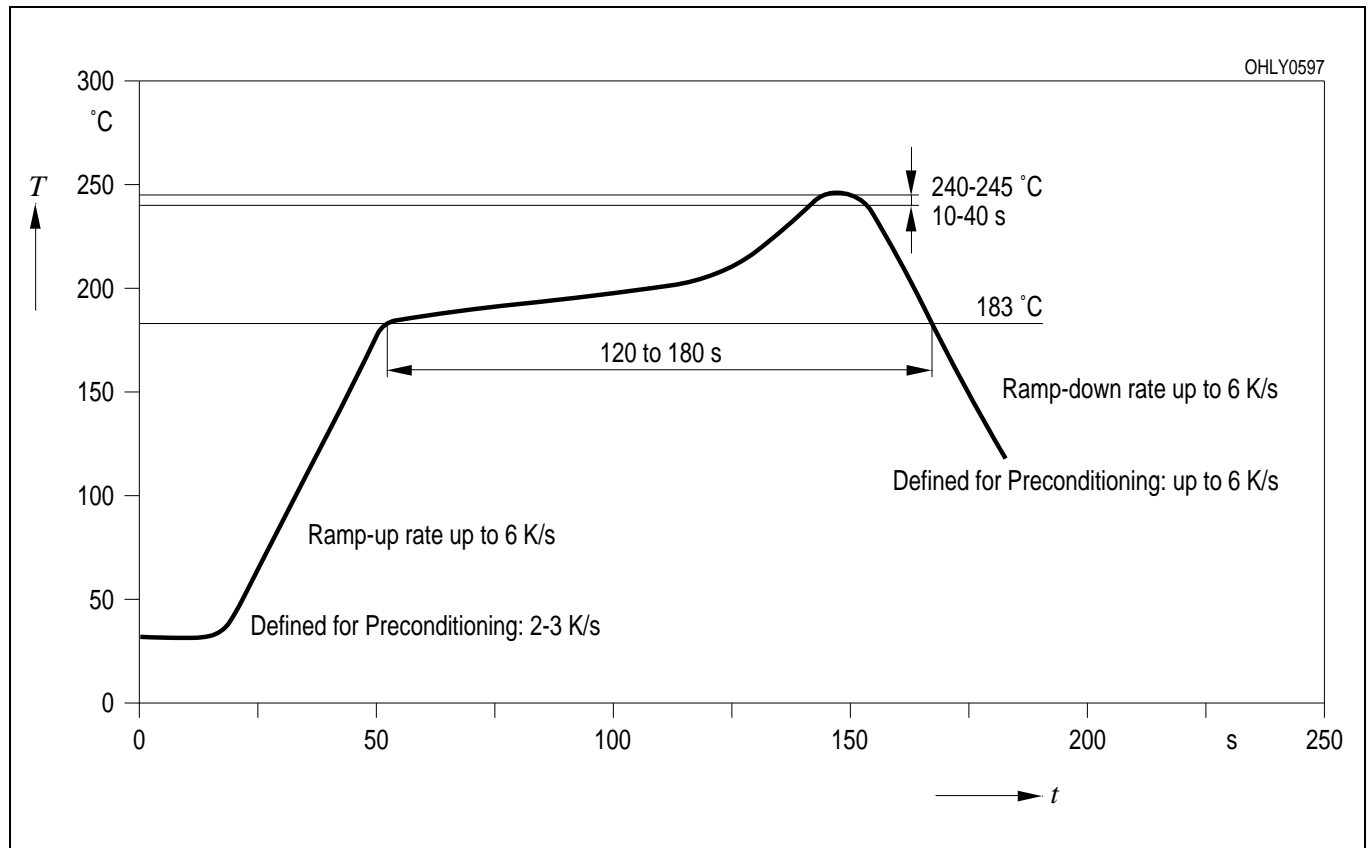


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

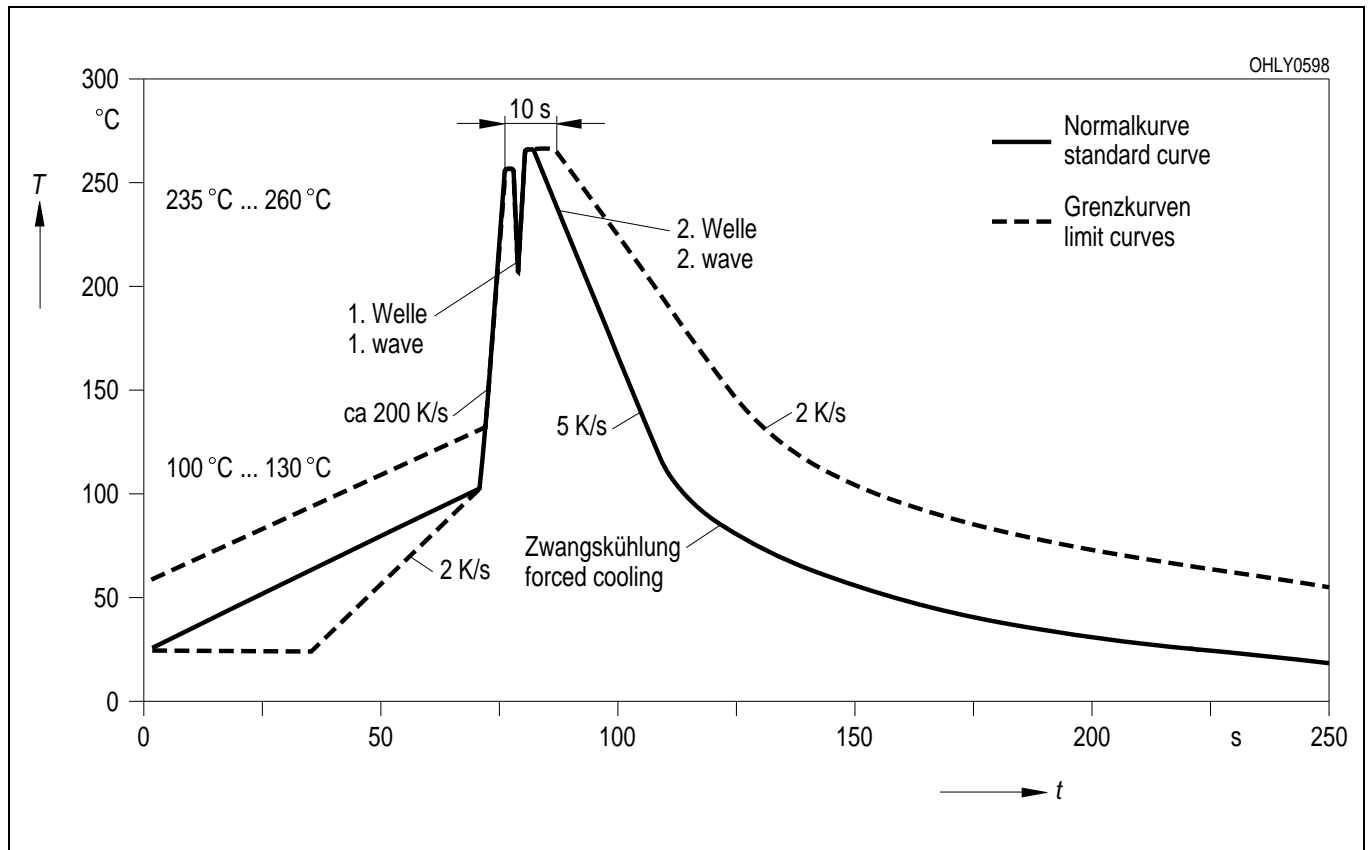
Kathodenkennung: abgeschrägte Ecke
Cathode mark: bevelled edge
Gewicht / Approx. weight: 40 mg

Lötbedingungen Vorbehandlung nach JEDEC Level 2
Soldering Conditions Preconditioning acc. to JEDEC Level 2

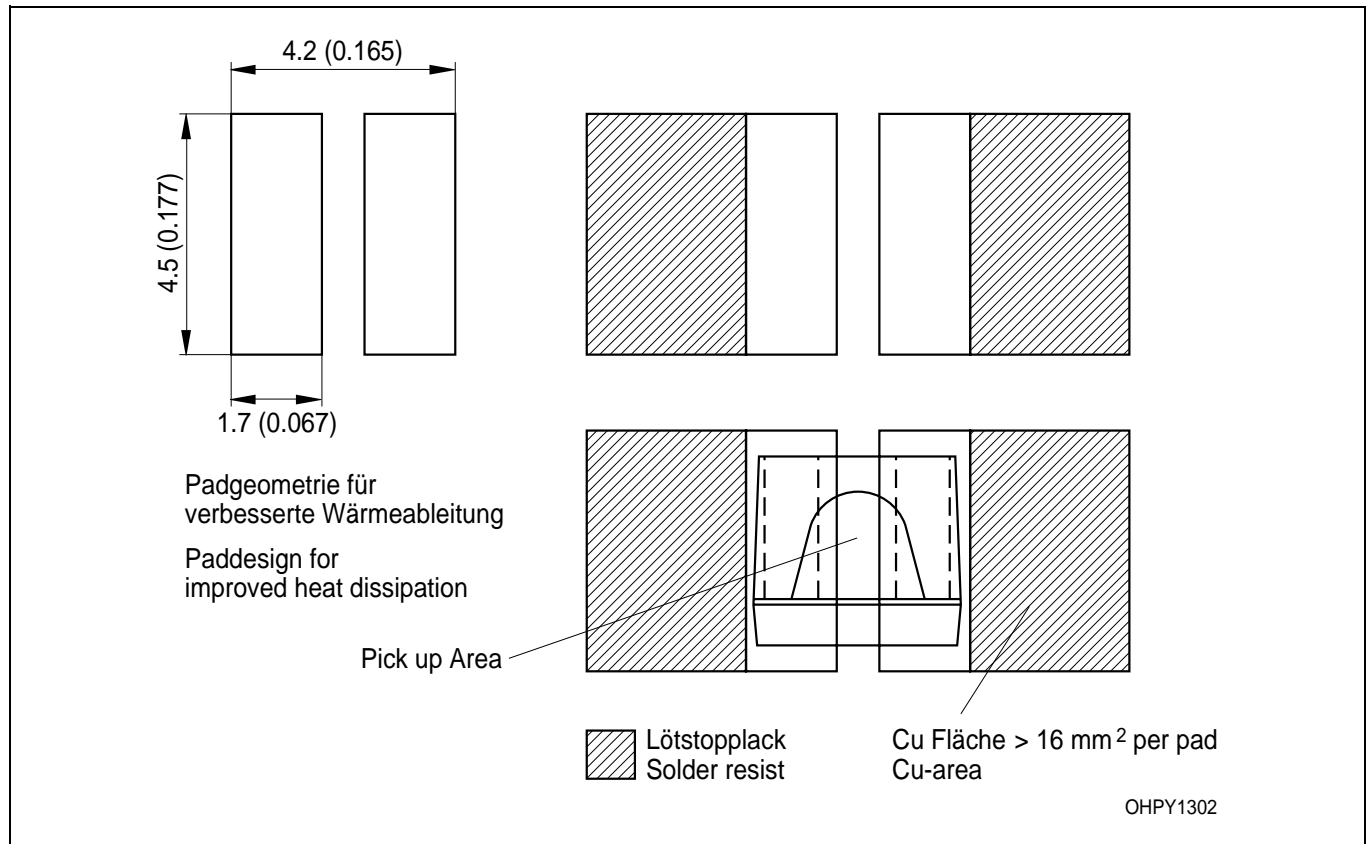
IR-Reflow Lötprofil (nach IPC 9501)
IR Reflow Soldering Profile (acc. to IPC 9501)



Wellenlöten (TTW) (nach CECC 00802)
TTW Soldering (acc. to CECC 00802)

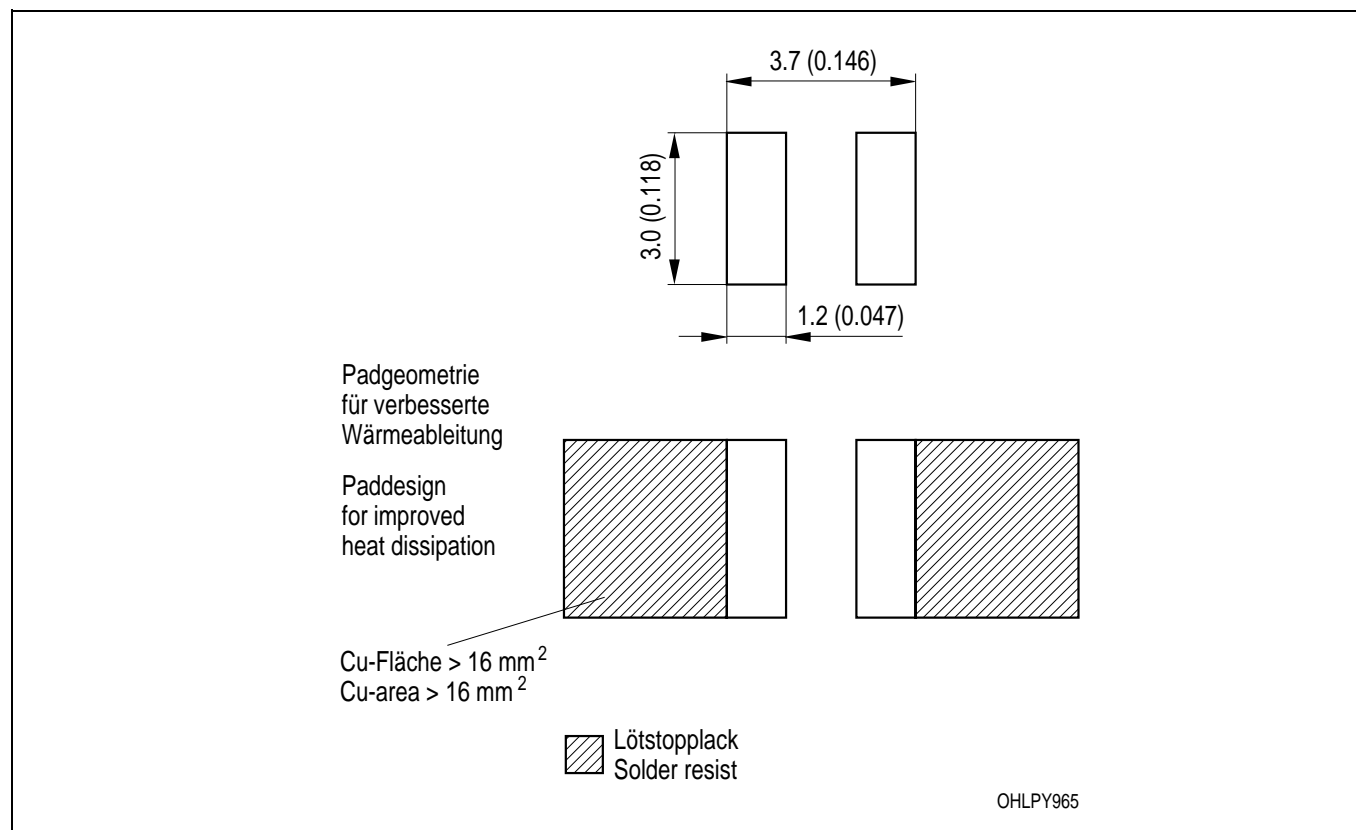


Empfohlenes Lötpad design Wellenlöten (TTW)
Recommended Solder Pad TTW Soldering



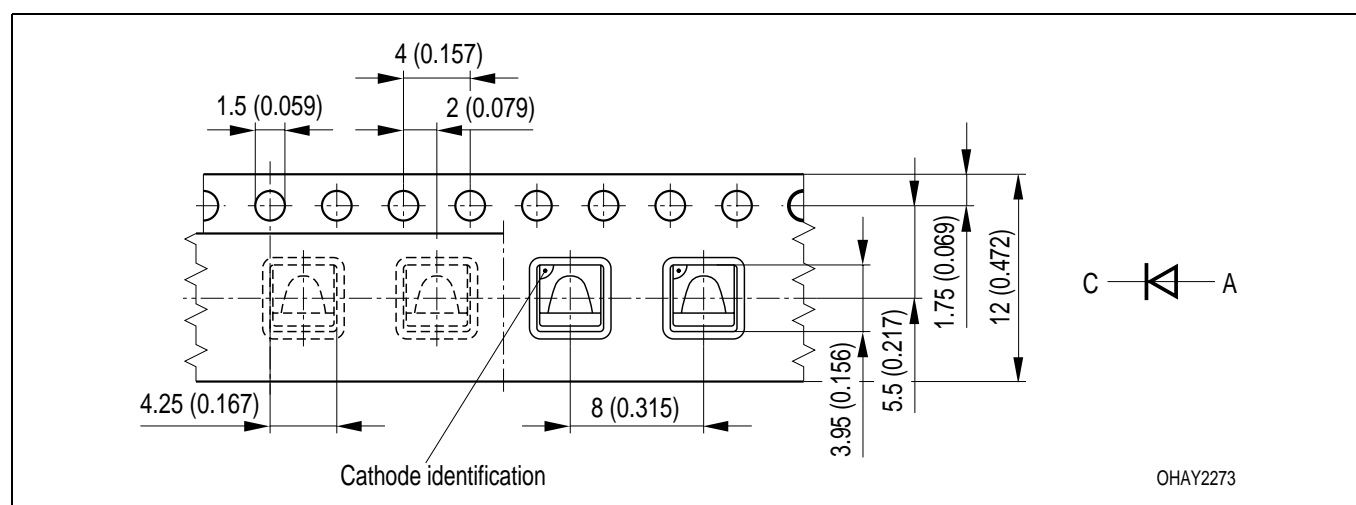
Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Empfohlenes Lötpaddesign IR Reflow Löten
Recommended Solder Pad IR Reflow Soldering



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Gurtung / Polarität und Lage Verpackungseinheit 2000/Rolle, ø330 mm
Method of Taping / Polarity and Orientation Packing unit 2000/reel, ø330 mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

Revision History: 2003-08-04		Date of change
Previous Version: 2002-11-18		
Page	Subjects (major changes since last revision)	
12	recommended solder pad	
12	recommended solder pad extended to TTW soldering	
13	annotations	2002-07-23
13	recommended solder pad (IR reflow soldering)	2002-08-01
3, 4	value (reverse voltage from 5 V to 12 V)	2002-09-18
all	not for new designs	2002-11-18
1, 2	Obsolete	2003-08-04

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Attention please!

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Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose! Critical components ¹ may only be used in life-support devices or systems ² with the express written approval of OSRAM OS.

¹ A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.

² Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.